The TNETW1100B from Texas Instruments (TI) combines the low power consumption, small size and superior transfer rates and range that are needed for embedded wireless local area networking (WLAN) in applications like laptop computers, cell phones, Internet appliances and personal digital assistants (PDA). The single-chip medium access controller (MAC) and baseband processor is fully compliant with the Wi-Fi (IEEE 802.11b) standard and is intended for Wi-Fi applications. Drawing on its decades-long experience with low-power operation in wireless telecommunications, TI optimized the TNETW1100B with Extra Low Power (ELP) technology, enabling a breakthrough standby power consumption of less than 2 milliWatts (mW) at the chip level yielding a 10 times reduction in standby power consumption at the system level over current 802.11 chipsets. With these power-saving features, system designers can avoid undesirable compromises like a second battery, large bulky batteries or unacceptably short usage times.

To save valuable board space in portable and consumer electronic systems, the TNETW1100B comes in a space-saving 12-x 12-mm, 179-pin ball grid array (BGA) package, which takes up 44 percent less board space than its predecessor. For existing designs, the TNETW1100B also comes in a 16-x 16-mm BGA package that is pin-for-pin compatible with its predecessor.

In addition to its breakthrough low-power consumption and reduced space requirements, the TNETW1100B achieves high performance in terms of data transfer rates and range. The device is capable of 802.11b Complementary Code Keying (CCK) encoding with up to 30-percent data throughput improvement allowing higher speeds at greater distances. The TNETW1100B also supports the optional Packet Binary Convolutional Coding (PBCC™) modulation scheme with rates up to 22 Mbps—twice the speed of 802.11b.

**Easy Integration Into Stations and Access Points**

The TNETW1100B supports the host and I/O interfaces needed for both 802.11 station and access point applications. These include 32-bit CardBus, PCI, USB 1.1, Compact-FLASH Plus, PCMCIA and a 16-bit generic slave.
To achieve better performance in noisy environments or settings with interference, the TNETW1100B's baseband processor has a multipath performance enhancement with an advanced receiver design, which provides a delay spread tolerance of greater than 500 nanoseconds (ns). To ensure security comparable with wired LANs, the TNETW1100B has Wired Equivalent Privacy (WEP) in hardware. The built-in WEP accelerator ensures that the security protocol will not adversely affect the system throughput. Software driver upgrades will include support for upcoming WLAN security enhancements.

**Embedded Station Driver Development Kit**
To enable customers' time-to-market, TI will offer a Driver Development Kit specifically targeted at embedded applications. This tool, called the eSTADK, will be fully optimized for mobile handheld applications such as cell phones or PDAs.

The eSTADK Operating System will be Windows® CE.

**For More Information**
Visit us at: [www.ti.com/wlan](http://www.ti.com/wlan)

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**TNETW1100B Features**

<table>
<thead>
<tr>
<th>Features</th>
<th>Benefits</th>
</tr>
</thead>
<tbody>
<tr>
<td>Industry’s lowest intra-beacon doze power consumption</td>
<td>Extends battery life, avoids compromise tradeoffs like additional batteries or limited usage times.</td>
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<tr>
<td>Small 12-x 12-mm BGA package</td>
<td>Smaller footprint saves board space in compact mobile system enclosures.</td>
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<tr>
<td>High-performance data throughput rates</td>
<td>Provides up to 30-percent improvement in CCK 11Mbps performance (greater throughput at longer distances) over other solutions plus PBCC™ mode providing 22 Mbit/sec. saving power by shortening communication times and returning to doze mode faster.</td>
</tr>
<tr>
<td>Single-chip MAC and baseband processor</td>
<td>Reduces bill of material, reducing overall system cost.</td>
</tr>
<tr>
<td>32-bit, 44-MHz ARM CPU</td>
<td>Powerful processing to maintain high throughput rates.</td>
</tr>
<tr>
<td>64 Kb of internal RAM</td>
<td>Eliminates need for external RAM, reducing BOM costs.</td>
</tr>
<tr>
<td>Direct memory access (DMA) to host memory in PCI and CardBus mode</td>
<td>Stores data in noncontiguous buffers, which reduces copy operations and saves system bandwidth for other tasks.</td>
</tr>
<tr>
<td>Antenna diversity support automatic</td>
<td>Selection of best antenna improves signal strength, increasing throughput by reducing re-transmissions.</td>
</tr>
</tbody>
</table>

**Comprehensive Development Packages**

- Complete hardware design kit (HDK)
- Windows® Software Package
- Manufacturing test support
- TI test system facility

- Reference design that includes schematics, layout, gerber files and radio control utility to enhance immediate hardware development.
- Complete set of Windows® Network Driver Interface Specifications (NDIS) drivers shorten time-to-market.
- 32-bit Windows® library supporting CardBus applications and allows for direct integration into volume manufacturing test program.
- Provides in-house test using FCC, Wi-Fi and WHQL test suites as well as TI-designed performance test suites.

**Standards Compliancy**

- Fully tested hardware reference design
- Drivers based on tested reference design
- Stamped with Windows® XP logo

- Intended for Wi-Fi compliant applications.
- Drivers are already WHQL-approved.
- Enhanced user confidence, knowing product was designed for Windows® XP.

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